	ζ.
	which demand high reliability, kindly contact our sales window correspondents.
	g
	õ
	gs
	ī
	႘
	low corresponde
	ğ
	ž
	Sé
	쎯
	S
ed.	2
hts Reserve	ಜ್ಞ
ese	ij
ř	ဗ
ηts	⋛
ğ	Ĕ.
<b>Y</b>	ty, kindly contact our sales windov
⋖	∄
Ξ.	abi
_	ē
<u>.</u>	≟
$\ddot{\circ}$	hig
$\overline{S}$	ď
<u>Y</u>	n demanc
Ŋ	ē
Ï	2
TI LI	힏
ઝ	⋛
ž	<u>8</u>
Ī	ē
24 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.	ive equipment / device whic
20	ì
Ħ	me
5	₽
ğ	adr
$\ddot{\circ}$	è
24	⋛
202	Ř
<u>.</u>	엄
<u>a</u>	₹
≥	ng
	usi
	ō
	ļ
	Ę
	era
	ğ
	Suc
	ರ
	ō
	ЭSЕ
	č
	_

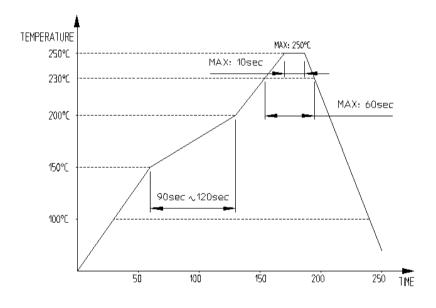
REV					BY	CHKD	DATE	REV	COUNT	DES	CRIPTION OF REVI	BY	CHKD	DA	TE	
<u> </u>	_ RE-2-1476(M.P. Release)			ase)	JSK	LHJ	20.05.22	<u> </u>	_	Revis	evised KYI			LHJ	21.1	2.15
/2\	Pevised				KYG	LHJ	21.08.23	$\triangle$								
					Universal Serial Bus Type-C Cable and Connector Specification Release 2.1 Universal Serial Bus Type-C Connectors and Cable Assemblies Compliance Document Revision 2.1b											
RATING CURRENT				1.25A Max. for each power pin (A1, A4, A9, A12, B1, B4, B5, B9, B12) 0.25A for the other pins												
VOLTAGE			48\	48V AC/DC												
	OPERATING CONDITION				-40℃ ~ +105℃ (INCLUDING TEMP. RISE), 95% RH max. (NON-CONDENSING)											
	STORAGE CONDITION -10° ~ +60° (WITH PACKING), 15% ~ 70% RH															
Para.	ara. Test Description				Test Procedure						Test Requirement					ΑТ
1	1 I Evamination of product I				A 364-18 sual inspection						No physical damage.				0	0
Elect	rical Re	quirer	ments													
2	EIA 364 Measure 2 Low Level Contact at 100m 4-wire r the resis					ssure at 20mV max open circuit 00mA (DC OR 1000Hz).					Initial: 40mΩ max for each contact After test: 50mΩ max for each contact					ı
3	With		ectric ng Voltage	Measur unmate	EIA 364-20 Measure per Method B with unmated condition. 100V AC RMS for 1 minute at sea level.						No disruptive discharge.					-
4	4 Insulation Resistance EIA 364-21 500V DC with unmated and mated condition.						1	100MΩ min.					-			
Mech	nanical	Requi	rements	<u> </u>												
5	Insertion force EIA 364-13 Measure at 12.5mm/minute min.							Initial & after test : 5N ~ 20N (with virgin plug)					_			
6	Extraction force EIA 364-13 Measure at 12.5mm/minute min.						Initial: 8N ~ 20N After test: 6N ~ 20N (with virgin plug)					-				
7		Dura	bility	Mated <sup>.</sup> Mechar Mating Insertio	EIA 364-09 Mated 10,000 times Mechanically operated : 500cycles/hr Mating stroke : 2.75mm nsertion, extraction force shall be measured at a maximum speed of 12.5mm/min						No physical damage.					
8	Ra	ındom	Vibration	Test Co Mated s betwee 15 mins	A 364-28 set Condition VII, Test Letter D ated specimens to 3.10 G's RMS stween 20 to 500Hz is minutes in each of 3 mutually expendicular planes.					d d	No physical damage. No discontinuity of 1µs of longer duration when mated connector during test.					1
REMARKS						DR	4FT	DES	SIGN	CHECK	APPR	OVAL	RELI	AS	E	
				S.K.	JANG		JANG		H.J.		DE	PT	$\overline{A}$			
								20.05.22 20.05.22 ENG				7				
NOTE) QT : QUALIFICATION TEST, AT : ASSURANCE TEST, O : Applicable Test																
DWG NO CL NO								PART NO								
ELC4-633111 CL (				6246-0001-7				CX90B1B-24P								
HIROSE KOREA COLLITO PRODUCT SPECIFICA					ΈΑΤΙ	 ON		1								

HS HIROSE KOREA.CO.,LTD

PRODUCT SPECIFICATION

Para.	Test Description	Test Procedure	Test Requirement	QT	ΑТ			
Environmental Requirements								
9	Temperature Life	EIA 364-17, Method A 105°C without applied voltage for 120 hours.	No physical damage.	0	-			
10	Cyclic Temperature and Humidity	EIA 364-31 25±3°C at 80±3% RH for 1 hour. 65±3°C at 50±3% RH for 1 hour. Thermal ramp: 0.5 hour Number of cycles: 24 cycles	No physical damage.	0	-			
11	Thermal Shock	EIA 364-32, Test Condition I 10 cycles -55°C and +105°C	No physical damage.	0	_			
12	Solderability	EIA 364-52 Dwell in 245±5℃ of the solder bath for 5 sec.	Solder coverage shall be 95% min. of the immersed surfaces.	0	-			
13	Salt Spray	EIA 364-26 Sample Condition: Reflow Soldered on PCB 5% of NaCl in 35°C for 48 hours.	No corrosions that affect to the connector operation.	0	_			
14	Reflow heat	Reflow profile [Fig.1] Peak 250°C max for 10 sec 2 times.	No deformation of mold No blister and popcorn	0	-			

REMARKS



[Fig.1] REFLOW TEMPERATURE

NOTE) QT: QUALIFICATION TEST, AT: ASSURANCE TEST, O: Applicable Test								
DWG NO	CL NO	PART NO						
ELC4-633111	CL 6246-0001-7	CX90B1B-24P						

HIS HIROSE KOREA.CO.,LTD

PRODUCT SPECIFICATION

## May.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved. In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

## Qualification Test Sequence Table

Doro	Took Description	Test Group									
Para.	Test Description	Α	В	С	D	E	F	G			
1	Examination of product	1,6	1,14	1,6	1,6	1,6	1,3	1,6			
2	Low Level Contact Resistance	3, 5	3, 11	3, 5	3, 5	3, 5		3, 5			
3	Dielectric Withstanding Voltage		4, 12								
4	Insulation Resistance		5, 13								
5	Insertion force		6, 9								
6	Extraction force		7, 10								
7	Durability		8								
8	Random Vibration	4									
9	Temperature Life			4							
10	Cyclic Temperature and Humidity				4						
11	Thermal Shock					4					
12	Solderability						2				
13	Salt Spray							4			
14	Reflow Heat	2	2	2	2	2		2			

## REMARKS

1) Numbers in the table above indicate the sequence corresponding to each test group.

NOTE) QT: QUALIFICATION TEST, AT: ASSURANCE TEST, O: Applicable Test

DWG NO CL NO PART NO

ELC4-633111 CL 6246-0001-7

CX90B1B-24P

